

Top

AA	AA	AA	AA	AA	AA	AA
FPHX2	FPHX2	FPHX2	FPHX2	FPHX2	FPHX2	FPHX2
AA	AA	AA	AA	AA	AA	AA
FPHX2	FPHX2	FPHX2	FPHX2	FPHX2	FPHX2	FPHX2
		YA	S4_DSCN5M...357			



T9BD Design Names

DED TSMC_025SPPM

Closer: SDR

05-NOV-2009 13:24:11

Top

AA	AA	AA	AA	AA	AA	AA
81650	81650	81650	81650	81650	81650	81650
AA	AA	AA	AA	AA	AA	AA
81650	81650	81650	81650	81650	81650	81650
		YA	900574			

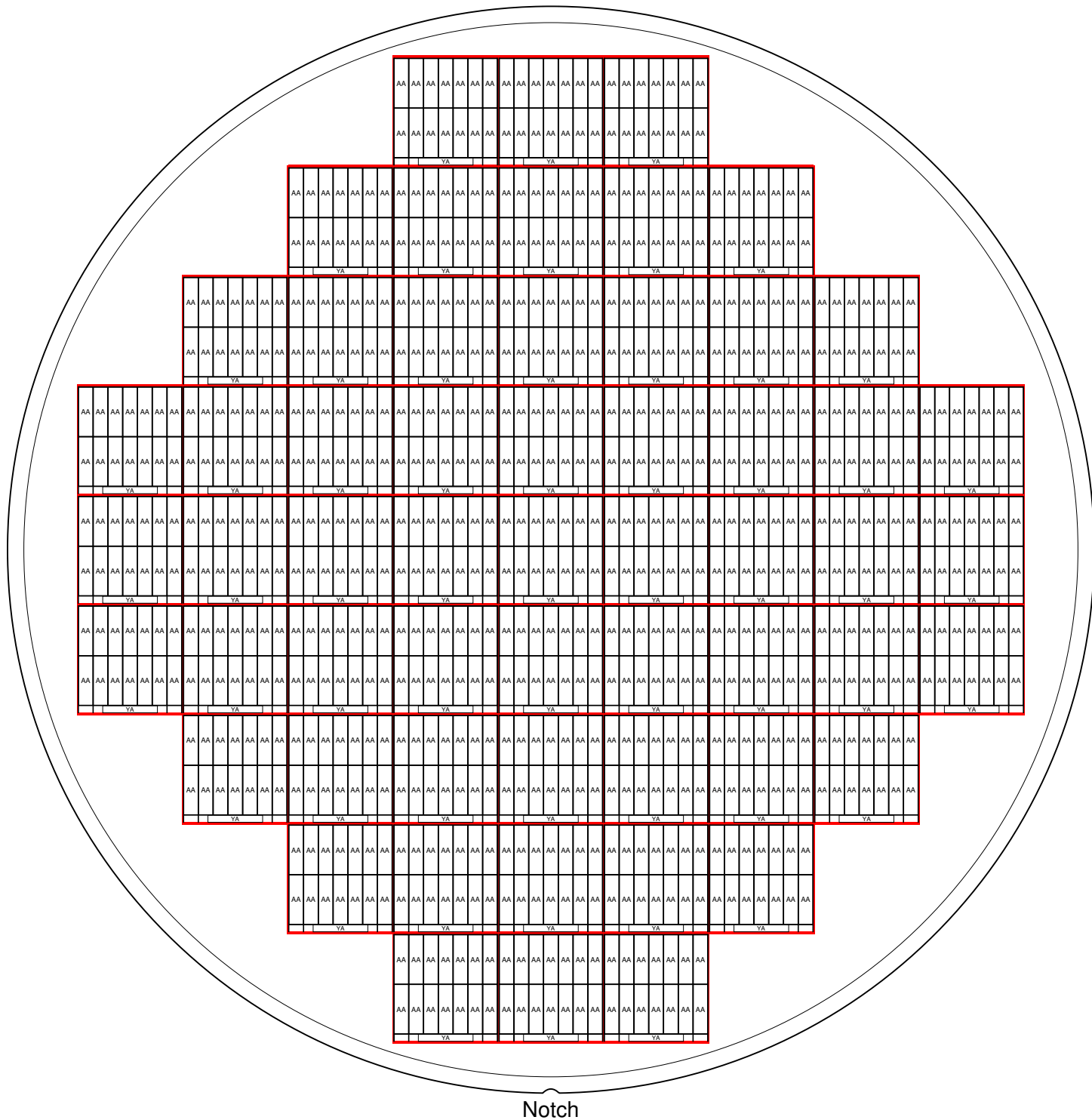


T9BD Design Numbers

DED TSMC_025SPPM

Closer: SDR

05-NOV-2009 13:24:13



PRELIMINARY - DO NOT DISTRIBUTE

 MOSIS	T9BD Detailed Step Pattern	D = 200000.0 um	DED TSMC_025SPPM
		X = 19362.52 um	Closer: SDR
		Y = 20156.88 um	05-NOV-2009 13:24:15

Project Wafer Summary

T9BD

Do not distribute, wafer lot is based on a preliminary stepping pattern.

Die ID	Design Name	Estimated Max Die Size X	Estimated Max Die Size Y	Estimated Quantity on Wafer
AA	FPHX2	2720.36	9148.94	798

Total on Wafer:				798

Estimated quantities based on die locations inside the tweezer margin that are not in partially processed reticle sites.